

## Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier               | User Part Number  |                                   |                 |            |           |  |
|------------------------|---|-----------------------------------|-----------------|------------|-----------|--|
| Nexperia B.V.          | PESD4USB3BBTTS-Q  |                                   |                 |            |           |  |
| Name of Laboratory     | Part Description  |                                   |                 |            |           |  |
| Nexperia ATGD          | NXP ICN8  |                                   | Protection INDI |            |           |  |
|                        | MCD package, Subcon UTAC  |                                   |                 |            |           |  |
| Based on AEC-Q101 Test | Test Conditions   | Duration                          | # Lots          | # Quantity | # Rejects |  |
| # E1                   | <b>TEST</b><br>Pre- and Post-Stress<br>Electrical Test<br>Tamb = 25 °C  | N/A                               | see below       | all parts  | see below |  |
| # A1                   | <b>PC</b><br>Preconditioning<br>JESD22-A113<br>Bake Tamb = 125 °C<br>Soak Tamb = 85 °C, RH = 85%<br>Reflow soldering  | 24 hours<br>168 hours<br>3 cycles | 69              | 3000       | 0         |  |
| # B1                   | <b>HTRB</b><br>High Temperature Reverse<br>Bias<br>MIL-STD-750-1<br>M1038 Method A<br>Tj = Tjmax, Vr = 100% of max. datasheet<br>reverse voltage              | 1000 hours                        | 30              | 1280       | 0         |  |
| # A4                   | <b>TC</b><br>Temperature Cycling<br>JESD22-A104<br>-65 °C to Tjmax, not to exceed 150°C   | 1000 cycles                       | 23              | 1000       | 0         |  |
| # A3 or                | <b>UHAST</b><br>Unbiased HAST<br>JESD22-A118<br>Tamb = 130 °C, RH = 85 %  | 96 hours                          | 23              | 1000       | 0         |  |
| # A3 alt               | <b>AC</b><br>Autoclave<br>JESD22-A102<br>Tamb = 121 °C, RH = 100 %<br>Pressure = 205 kPa (29.7 psia)  |                                   |                 |            |           |  |
| # A2 alt               | <b>H3TRB</b><br>High Humidity High<br>Temperature Reverse Bias<br>JESD22-A101<br>Tamb = 85 °C, RH = 85%, VR = 80 % of<br>rated reverse voltage <sup>[1]</sup> | 1000 hours                        | 23              | 1000       | 0         |  |
| # A5                   | <b>IOL</b><br>Intermittent Operating Life<br>MIL-STD-750 Method 1037<br>ton = toff, devices powered to insure ΔTj =<br>100 °C for 15000 cycles                | 1000 hours                        | n.a.            | n.a.       | n.a.      |  |
| # C8                   | <b>RSH</b><br>Resistance to Solder Heat<br>JESD22-A111<br>260 °C ± 5 °C   | 10 s                              | n.a.            | n.a.       | 0         |  |
| # C10                  | <b>SD</b><br>Solderability<br>J-STD-002   |                                   | 21              | 630        | 0         |  |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

### Calculation of FIT and MTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology      | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|-----------------|----------|---------|--------------------|------------|
| NXP ICN8  | Protection INDI | 1280     | 0       | 3,32               | 3,01E+08   |

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